

## PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>QIYANG HE</td> <td>01/07/2014</td> </tr> <tr> <td>CHENGLONG ZHANG</td> <td>01/07/2014</td> </tr> </tbody> </table>		Name	Execution Date	QIYANG HE	01/07/2014	CHENGLONG ZHANG	01/07/2014
Name	Execution Date						
QIYANG HE	01/07/2014						
CHENGLONG ZHANG	01/07/2014						
RECEIVING PARTY DATA							
Name:	SEMICONDUCTOR MANUFACTURING INTERNATIONAL (BEIJING) CORPORATION						
Street Address:	NO. 18, WEN CHANG RD., ECONOMIC-TECHNOLOGICAL, DEVELOPMENT AREA, DAXING DISTRICT,						
City:	BEIJING						
State/Country:	CHINA						
Postal Code:	100716						
Name:	SEMICONDUCTOR MANUFACTURING INTERNATIONAL (SHANGHAI) CORPORATION						
Street Address:	18 ZHANGJIANG ROAD, PUDONG NEW AREA,						
City:	SHANGHAI						
State/Country:	CHINA						
Postal Code:	201203						
PROPERTY NUMBERS Total: 1							
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14161740</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14161740		
Property Type	Number						
Application Number:	14161740						
CORRESPONDENCE DATA							
Fax Number:							
Phone:	571-379-9468						
Email:	docketing@anovallaw.com						
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>							
Correspondent Name:	ANOVA LAW GROUP C/O SMIC						
Address Line 1:	21351 GENTRY DRIVE						

Address Line 2: SUITE 150  
Address Line 4: STERLING, VIRGINIA 20166

ATTORNEY DOCKET NUMBER:	00158.0159.00US
NAME OF SUBMITTER:	GRACE GAO
Signature:	/Grace Gao/
Date:	01/23/2014

Total Attachments: 2  
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Anova Law Group, PLLC 00158.0159.00US

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## ASSIGNMENT

WHEREAS I/We, the below named inventor(s) (hereinafter referred to as Assignor(s)) have made an invention entitled:

### CAPACITIVE PRESSURE SENSORS AND FABRICATION METHODS THEREOF

for which I/We executed an application for United States Letters Patent concurrently herewith or filed an application for United States Letters Patent on \_\_\_\_\_ (Application No. \_\_\_\_\_); and

WHEREAS, Semiconductor Manufacturing International (Beijing) Corporation, a corporation of P. R. China whose post office address is No. 18, Wen Chang Rd., Economic-Technological, Development Area, Daxing District, Beijing, China, 100716, and Semiconductor Manufacturing International (Shanghai) Corporation, a corporation of P. R. China whose post office address is 18 Zhangjiang Road, Pudong New Area, Shanghai, China 201203 (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, I/We, as Assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, my/our entire right, title, and interest in and to this invention, provisional Application No. \_\_\_\_\_, filed \_\_\_\_\_ (if any), and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of the above provisional application (if any), as well as all rights to claim priority on the basis of this application, and all applications for Letters Patent which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and I/We hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent for this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY covenant that I/We have the full right to convey the interest assigned by this Assignment, and I/We have not executed and will not execute any agreement in conflict with this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me/us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/we have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. \_\_\_\_\_, filed \_\_\_\_\_) the filing date and application number of said application when known.

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IN TESTIMONY WHEREOF, I/We have hereunto set our hands.

Inventor 1:

Name: QIYANG HE  
Address: 18 Zhangjiang Road, Pudong New Area  
Shanghai, China 201203  
Signature: Qi Yang He  
Date: 2014. 1. 7

Inventor 2:

Name: CHENGLONG ZHANG  
Address: 18 Zhangjiang Road, Pudong New Area  
Shanghai, China 201203  
Signature: CHENGLONG ZHANG  
Date: 2014. 1. 7